

C2129A

Conductor

Description

C2129A is a high performance mixed bonded Ag/Pd conductor material. It offers cost savings over standard Ag/Pd formulations while maintaining the advantages of leach resistance and aged adhesion. C2129A is also aluminum wire bondable. C2129A is supplied with a rheology, which results in a dense, uniform fired film.

Key Features

- Low cost
- Excellent solderability and leach resistance
- Low resistivity
- Good Al wire bond adhesion (initial and aged)



This picture does not show the packaging of C2129A and is solely intended for illustration purposes. The products are available in different packaging configurations and may change over time. Please refer to the latest safety data sheets for safety-relevant pictograms.

Typical Properties

Viscosity	120-180 Kcps Brookfield HBTSC4-14 spindle, 6R utility cup at 10 rpm, 25 °C
Solids	80.0 ± 1.0 %
Alloy Ratio	30:01:00
Coverage	85 cm ² /g at 12 um fired film thickness
Metal	AgPd
Color	Dark Grey

Recommended Processing Guide

Process Temperature (TDS)	850 °C peak temperature. Dwell time at peak temperature for 10 minutes.
Film Thickness	10-15 um

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Warranty

6 months

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